

Bavani Balakrisnan

List of Publications by Year in descending order

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13
papers

393
citations

840776

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1199594

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13
all docs

13
docs citations

13
times ranked

494
citing authors

#	ARTICLE	IF	CITATIONS
1	Design of compliant meanders for applications in MEMS, actuators, and flexible electronics. Smart Materials and Structures, 2012, 21, 075033.	3.5	13
2	Edge Effects Determine the Direction of Bilayer Bending. Nano Letters, 2011, 11, 2280-2285.	9.1	127
3	Batch fabricated bidirectional dielectric elastomer actuators. , 2011, , .		4
4	Elasticity modulus, hardness and fracture toughness of Ni ₃ Sn ₄ intermetallic thin films. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2006, 423, 107-110.	5.6	48
5	Highly efficient electroluminescent biphenyl-substituted poly(p-phenylenevinylene)s through fine tuning the polymer structure. Polymer, 2006, 47, 1820-1829.	3.8	17
6	Enhanced morphological stability of NiGe films formed using Ni(Zr) alloy. Thin Solid Films, 2006, 504, 104-107.	1.8	27
7	Growth of high quality Er-Ge films on Ge(001) substrates by suppressing oxygen contamination during germanidation annealing. Thin Solid Films, 2006, 504, 81-85.	1.8	11
8	A study of charge mobility characteristics in a series of biphenyl substituted PPV derivatives. Chemical Physics Letters, 2005, 414, 393-397.	2.6	11
9	Texture of NiGe on Ge(001) and its evolution with formation temperature. Applied Physics Letters, 2005, 87, 241922.	3.3	28
10	Fracture toughness of Cu-Sn intermetallic thin films. Journal of Electronic Materials, 2003, 32, 166-171.	2.2	35
11	Influence of Carbon Sputtering Conditions on Corrosion Protection of Magnetic Layer by an Electrochemical Technique. Journal of the Electrochemical Society, 2002, 149, B84.	2.9	13
12	Electrochemical tests on the carbon protective layer of a hard disk. Diamond and Related Materials, 2002, 11, 1409-1415.	3.9	21
13	Failure mechanism of lead-free solder joints in flip chip packages. Journal of Electronic Materials, 2002, 31, 1256-1263.	2.2	38